OKAYA Electric America, Inc.

SPECIFICATIONS

DRAWING CODE _____

SAMPLE CODE _____

(This Code will be changed while mass production)

MASS PRODUCTION CODE **RH240320T-2x4WN-B2**

Customer Approved

Date:

Sales Sign	QC Confirmed	Checked By	Designer

Approval for Specifications Only

This specification is subject to change without notice

Approval for Specifications and Sample

OKAYA

Phone: 219-477-4488
Fax: 219-477-4856
www.okaya.com

OKAYA ELECTRIC AMERICA
52 Marks Road, Suite 1
Valparaiso, Indiana 46383

NO.PT-A-005-8

History of Version

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
06/09/2010	**01**	**001**	**New drawing**	**-**	**Anton**
09/28/2011	**01**	**002**	**The sample spec**	**-**	**Jacob**

Total: 25 Page

Contents

1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	240 * (R、G、B) * 320 Dots
LCD Type	a-Si TFT , Normally white TN mode , Transmissive
Screen size(inch)	2.4 (Diagonal)
Viewing Direction	12 O'clock
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	16-bit interface for i80system
Other(controller / driver IC)	ST7781R
ROHS	THIS PRODUCT CONFORMS THE ROHS OF OKAYA

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	42.72 (W) * 60.26 (L) * 2.5 (H)	mm

LCD Panel

Item	Standard Value	Unit
Viewing Area	38.72 (W) * 50.96 (L)	mm
Active Area	36.72 (W) * 48.96 (L)	mm

Note : For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Module

Item	Symbol	Condition	Min.	Max.	Unit
System Power Supply Voltage	VCC	-	-0.3	+4.6	V
	VGH-GND	-	-0.3	+15	V
	GND-VGL	-	-0.3	+13	V
Input Voltage	VIN	-	-0.3	IOVCC+0.3	V
Operating Temperature*1	T_{OP}	-	-20	+70	°C
Storage Temperature*1	T_{ST}	-	-30	+80	°C
Storage Humidity	H_D	Ta ≦ 60 °C	20	90	%RH

Note1:This value is not suitable for touch panel.

1.4 DC Electrical Characteristics

Module GND = 0V, Ta = 25°C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply Voltage1	VCC	-	-	2.8	-	V
Input High Voltage	V_{IH}	-	0.8*IOVCC	-	IOVCC	V
Input Low Voltage	V_{IL}	-	-0.3	-	0.2*IOVCC	V
Output High Voltage	V_{OH}	IOH=-0.1mA	0.8*IOVCC	-	-	V
Output Low Voltage	V_{OL}	IOL=0.1mA	-	-	0.2*IOVCC	V
Supply Current	IDD	VCC= 2.8V, Pattern=Black *2	-	6	9	mA

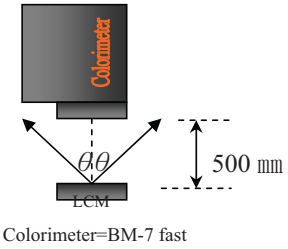
Note2 : Maximum current display

1.5 Optical Characteristics

TFT LCD Panel VCC = 2.8V, Ta=25°C

Item		Symbol	Condition	Min.	Typ.	Max.	unit	
Response time		Tr + Tf	Ta = 25°C θX, θY = 0°	-	31	36	ms	Note2
Viewing angle	Top	θY+	CR ≥ 10	-	40	-	Deg.	Note4
	Bottom	θY-		-	15	-		
	Left	θX-		-	40	-		
	Right	θX+		-	40	-		
Contrast ratio		CR	Ta = 25°C θX , θY = 0°	150	200	-	-	Note3
Color of CIE Coordinate (With B/L)	White	X		0.24	0.29	0.34	-	Note1
		Y		0.26	0.31	0.36		
	Red	X		0.58	0.63	0.68		
		Y		0.29	0.34	0.39		
	Green	X		0.30	0.35	0.40		
		Y		0.53	0.58	0.63		
	Blue	X		0.10	0.15	0.20		
		Y		0.04	0.09	0.14		
Average Brightness Pattern=white display (With B/L)		IV	IF= 80mA	170	190	-	cd/m^2	Note1
Uniformity (With B/L)		△B	IF= 80mA	80	-	-	%	Note1

Note1:
1：△B=B(min) / B(max) × 100%
2：Measurement Condition for Optical Characteristics:
a：Environment: 25℃±5℃ / 60±20%R.H，no wind，dark room below 10 Lux at typical lamp current and typical operating frequency.
b：Measurement Distance: 500 ± 50 ㎜ ，(θ= 0°)
c：Equipment: TOPCON BM-7 fast，(field 1°)，after 10 minutes operation.
d：The uncertainty of the C.I.E coordinate measurement ±0.01，Average Brightness ± 4%

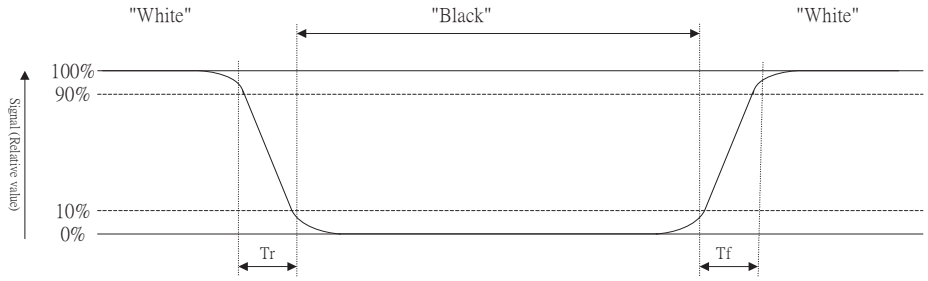


Colorimeter=BM-7 fast

Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from “black” to “white”(falling time) and from “white” to “black”(rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



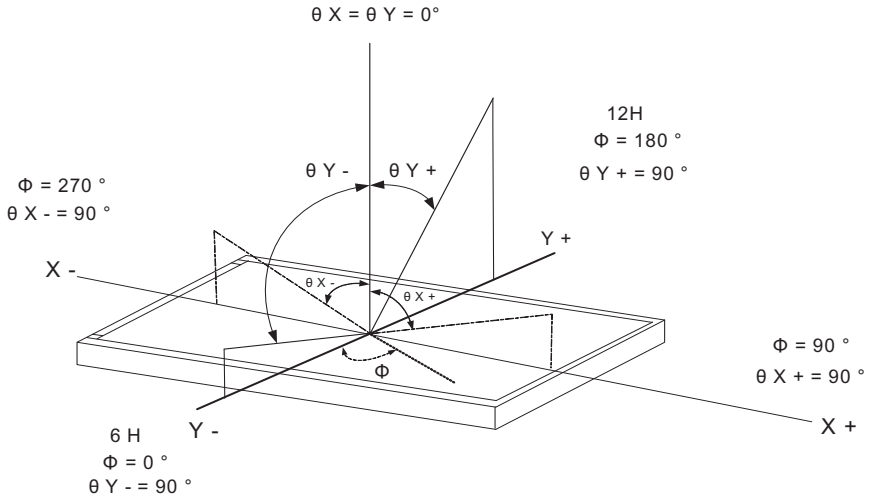
Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at “White” state}}{\text{Photo detector output when LCD is at “Black” state}}$$

Note4: Definition of viewing angle:

Refer to figure as below:



1.6 Backlight Characteristics

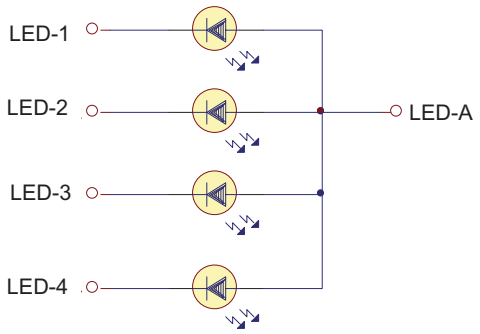
Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25℃	-	120	mA
Reverse Current	IR	Ta =25℃	-	0.2	mA
Forward Voltage	VF	Ta =25℃		4	V
Reverse Voltage	VR	Ta =25℃	-	5	V
Power Dissipation	PD	Ta =25℃	-	480	mW

Electrical / Optical Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage	VF	IF= 80mA	3.1	3.3	3.6	V
Average Brightness (without LCD)	IV	IF= 80mA	3800	4200	-	cd/m^2
Color of CIE Coordinate (without LCD)	X		0.25	0.28	0.31	-
	Y		0.25	0.28	0.31	
Color	White					

Internal Circuit Diagram :



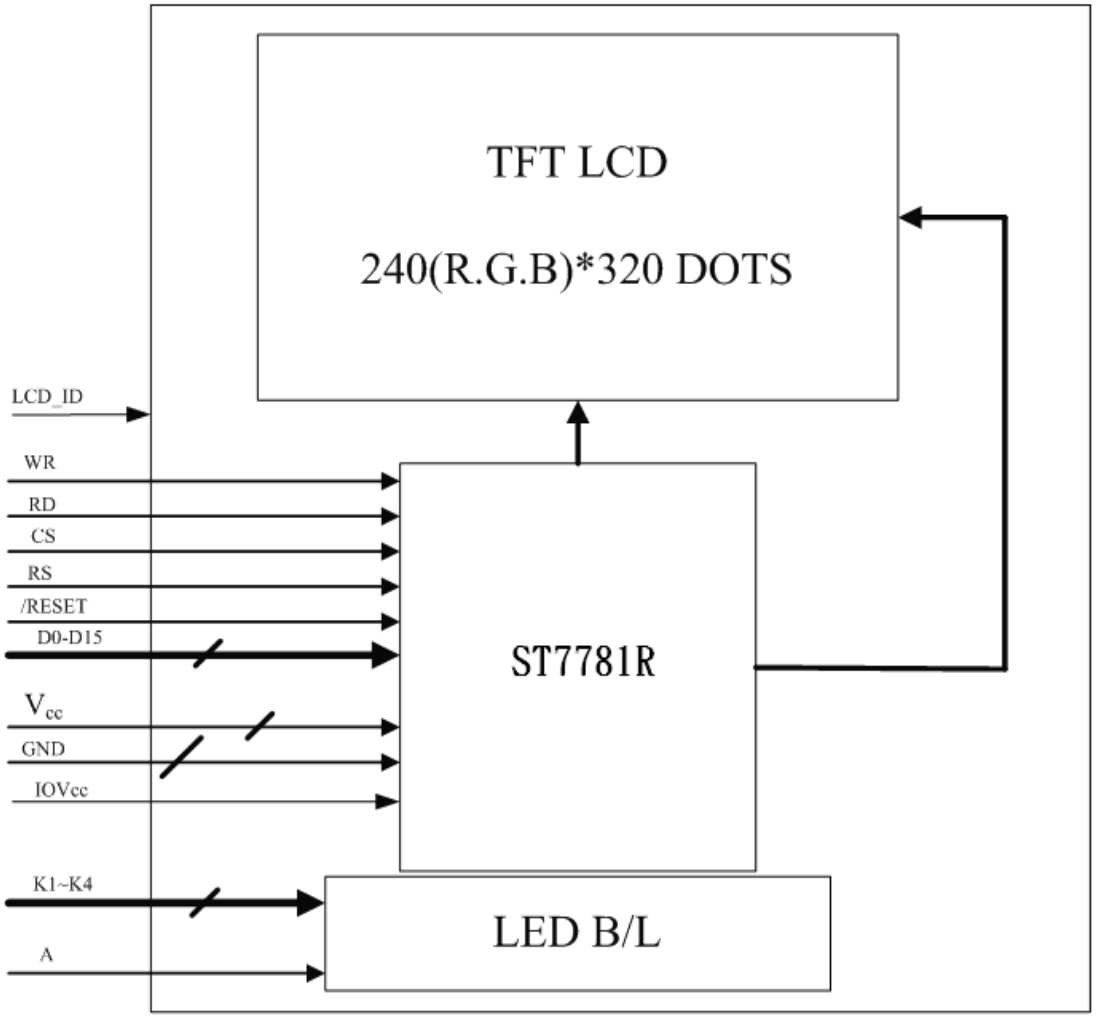
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram



2.2 Interface Pin Description

Pin No.	Symbol	Function
1	GND	System ground. (0V)
2	Y-	Not connected. Left open.
3	X-	Not connected. Left open.
4	Y+	Not connected. Left open.
5	X+	Not connected. Left open.
6	GND	System ground. (0V)
7	NC	Not connected. Left open.
8	NC	Not connected. Left open.
9	NC	Not connected. Left open.
10	NC	Not connected. Left open.
11	LCD_ID	LCD indicate pin
12	/RESET	Reset signal. Active at 'L'. Be sure to execute a power-on reset after supplying power.
13	NC	Not connected. Left open.
14	NC	Not connected. Left open.
15	D15	16-bit parallel data bus for MPU system interface mode.
16	D14	
17	D13	
18	D12	
19	D11	
20	D10	
21	D9	
22	D8	
23	D7	
24	D6	
25	D5	
26	D4	
27	D3	
28	D2	

Pin No.	Symbol	Function
29	D1	16-bit parallel data bus for MPU system interface mode.
30	D0	
31	RD	Read strobe signal. Active at ‘L’.
32	WR	Write strobe signal. Active at ‘L’.
33	RS	Register select signal. When RS=’L’: Select a index or a status register; When RS=’H’: select a control register.
34	CS	Chip select signal. Active at ‘L’.
35	GND	System ground.(0V)
36	IOVCC	Power supply to the interface pins. (+2.8V)
37	VCC	Power supply to the internal logic. (+2.8V)
38	VCC	Power supply to the internal logic. (+2.8V)
39	K4	Power supply for LED Backlight cathode input.
40	K3	Power supply for LED Backlight cathode input.
41	K2	Power supply for LED Backlight cathode input.
42	K1	Power supply for LED Backlight cathode input.
43	A	Power supply for LED Backlight anode input.
44	GND	System ground. (0V)

2.3 Timing Characteristics

2.3.1 80-System Bus Interface

VCC=2.8V，Ta=25℃

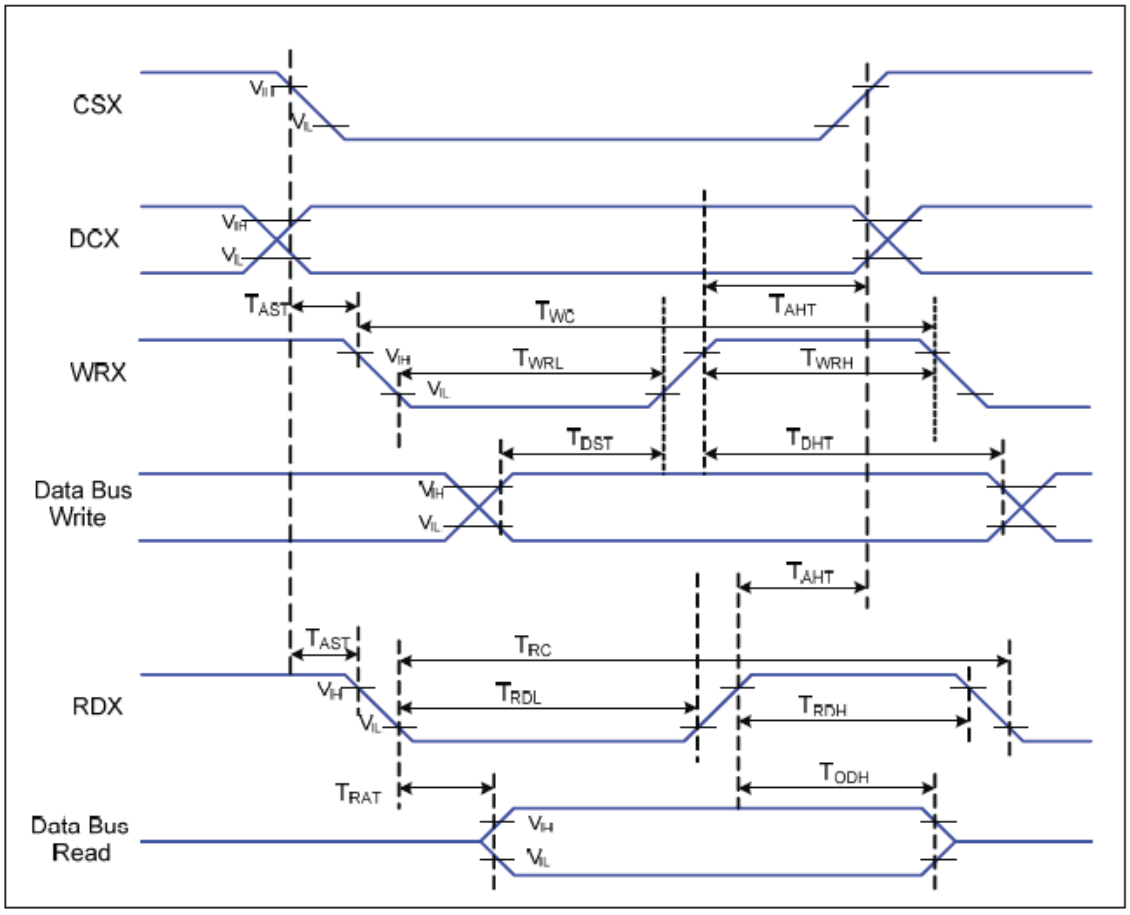


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

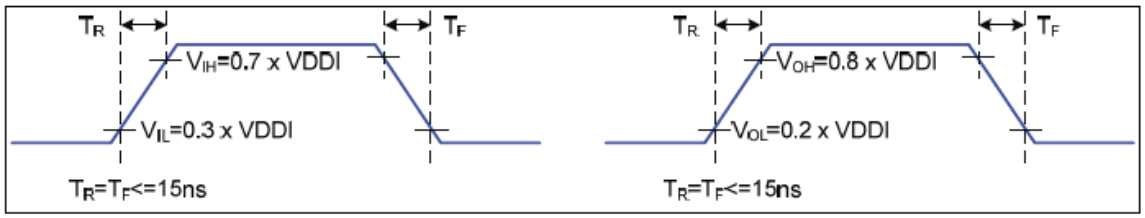


Figure 2 Rising and Falling Timing for I/O Signal

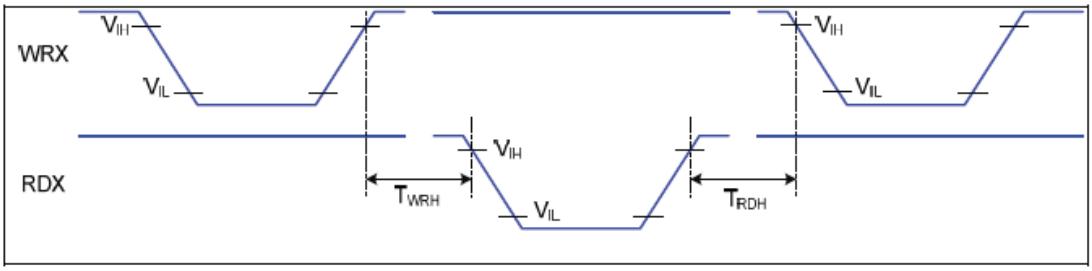


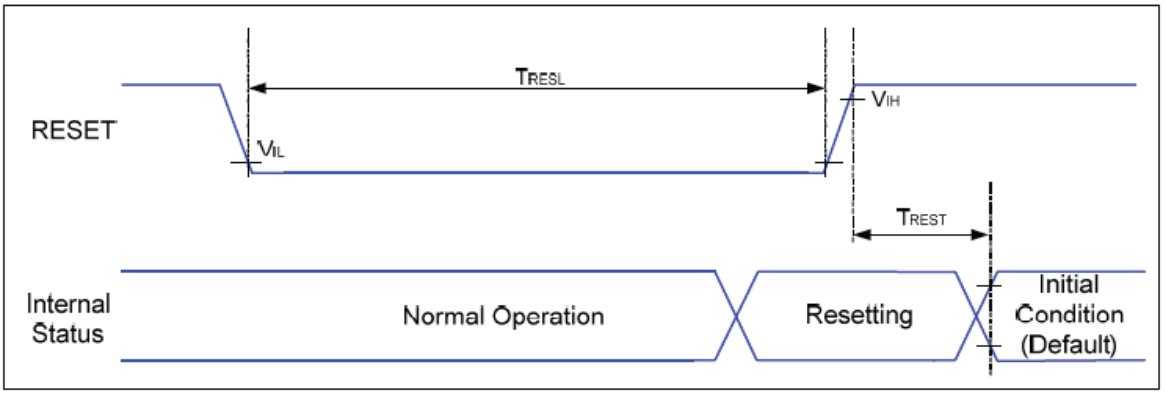
Figure 3 Write-to-Read and Read-to-Write Timing

VCC=2.8V，Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
DCX	TAST	Address Setup Time	10	-	ns	
	TAHT	Address Hold Time (Write/Read)	5	-	ns	
WRX	TWC	Write Cycle	100	-	ns	
	TWRH	Control Pulse "H" Duration	50	-	ns	
	TWRL	Control Pulse "L" Duration	50	-	ns	
RDX	TRC	Read Cycle (ID)	300	-	ns	When Read ID Data
	TRDH	Control Pulse "H" Duration (ID)	150	-	ns	
	TRDL	Control Pulse "L" Duration (ID)	150	-	ns	
DB[17:0]	TDST	Data Setup Time	10	-	ns	TRAT, TRATFM: 3K ohm Pull up or Down and 30pF Parallel Cap. To GND. TODH: 3K ohm Pull up or Down.
	TDHT	Data Hold Time	15	-	ns	
	TRAT	Read Access Time (ID)	-	100	ns	
	TODH	Output Disable Time	50	-	ns	

2.3.2 Reset Timing Characteristic

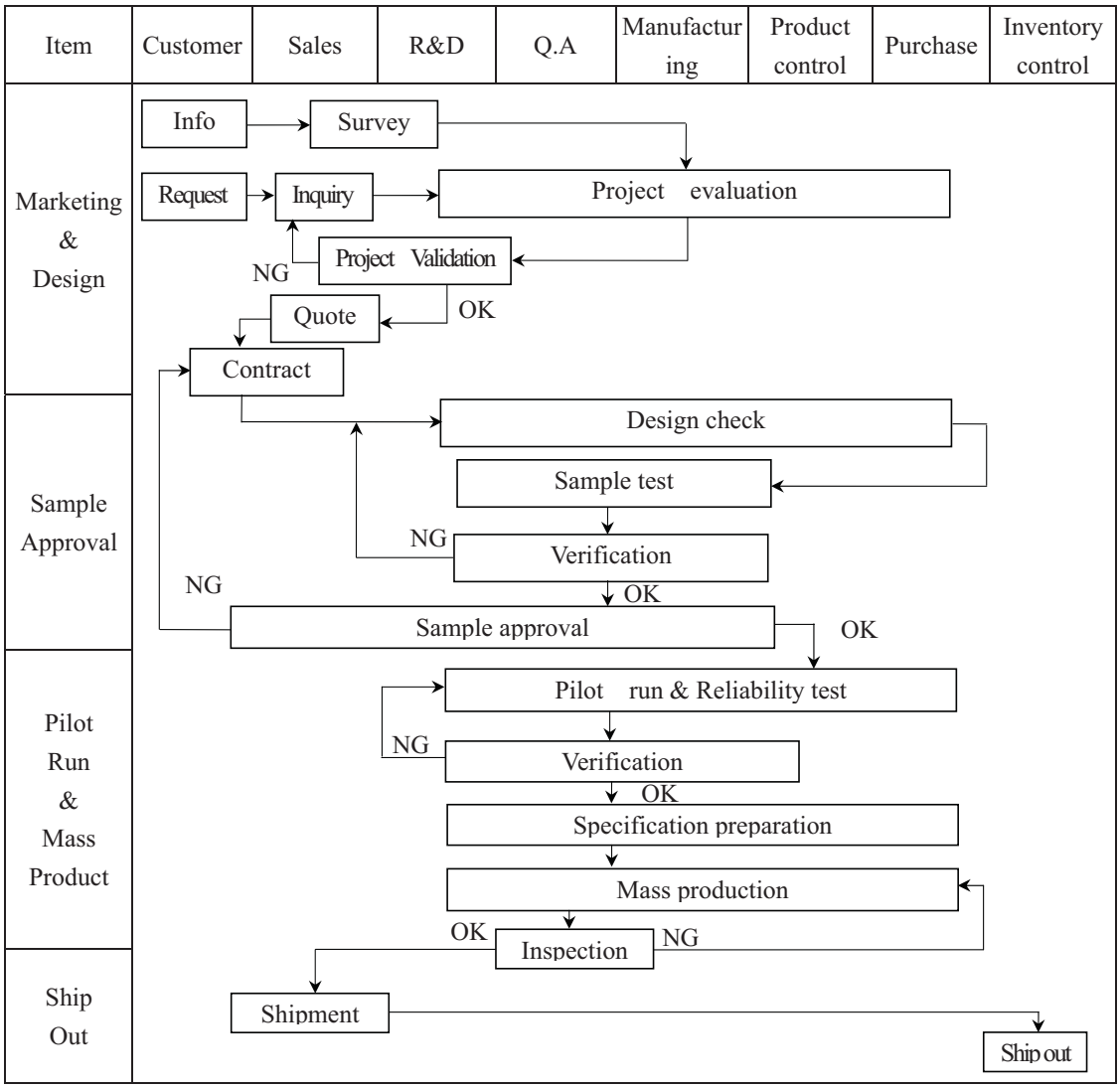
VCC=2.8V，Ta=25℃

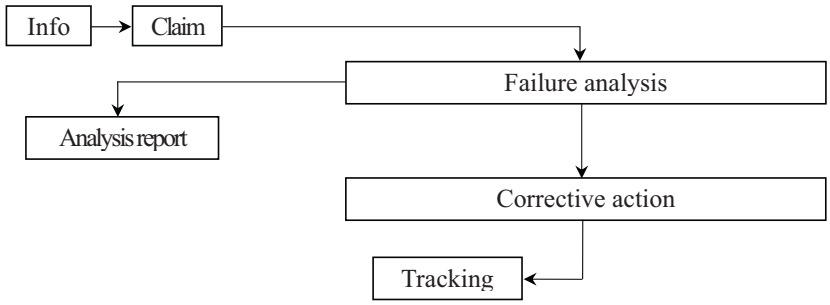


Signal	Symbol	Parameter	Min	Max	Unit	Description
RESET	TRESL	Reset Low Level Width	1	-	ms	-
	TREST	Reset Complete Time	1		ms	

3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart



Item	Customer	Sales	R&D	Q.A	Manufacturing	Product control	Purchase	Inventory control
Sales Service								
Q.A Activity	1. ISO 9001 Maintenance Activities 2. Process improvement proposal 3. Equipment calibration 4. Education And Training Activities 5. Standardization Management							

3.2. Inspection Specification

◆Scope ：The document shall be applied to TFT-LCD Module for less than 3.5″ (Ver.B01).

◆Inspection Standard：MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment：Gauge、MIL-STD、Powertip Tester、Sample

◆Defect Level：Major Defect AQL： 0.4 ； Minor Defect AQL： 1.5

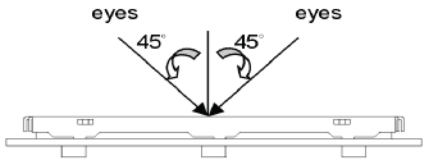
◆OUT Going Defect Level：Sampling.

◆Standard of the product appearance test：

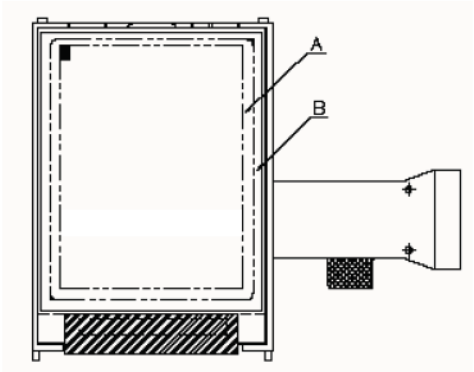
a. Manner of appearance test：

(1). The test best be under 20W×2 fluorescent light，and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area : viewing area

B area : Outside of viewing area

(4). Standard of inspection： (Unit：mm)

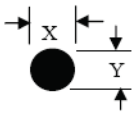
◆Specification For TFT-LCD Module Less Than 3.5″： (Ver.B01)

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td rowspan="3">01</td><td rowspan="3">Product condition</td><td>1.1 The part number is inconsistent with work order of production.</td><td>Major</td></tr>
<tr><td>1.2 Mixed product types.</td><td>Major</td></tr>
<tr><td>1.3 Assembled in inverse direction.</td><td>Major</td></tr>
<tr><td>02</td><td>Quantity</td><td>2.1 The quantity is inconsistent with work order of production.</td><td>Major</td></tr>
<tr><td>03</td><td>Outline dimension</td><td>3.1 Product dimension and structure must conform to structure diagram.</td><td>Major</td></tr>
<tr><td rowspan="5">04</td><td rowspan="5">Electrical Testing</td><td>4.1 Missing line character and icon.</td><td>Major</td></tr>
<tr><td>4.2 No function or no display.</td><td>Major</td></tr>
<tr><td>4.3 Display malfunction.</td><td>Major</td></tr>
<tr><td>4.4 LCD viewing angle defect.</td><td>Major</td></tr>
<tr><td>4.5 Current consumption exceeds product specifications.</td><td>Major</td></tr>
<tr><td>05</td><td>Dot defect
(Bright dot、Dark dot)
On -display</td><td>
<table>
<tr><th colspan="2">Item</th><th>Acceptance (Q'ty)</th></tr>
<tr><td rowspan="4">Dot Defect</td><td>Bright Dot</td><td>≦ 2</td></tr>
<tr><td>Dark Dot</td><td>≦ 3</td></tr>
<tr><td>Joint Dot</td><td>≦ 2</td></tr>
<tr><td>Total</td><td>≦ 3</td></tr>
</table>
5.1 Inspection pattern：full white , full black , Red , Green and blue screens.
5.2 It is defined as dot defect if defect area ＞1/2 dot.
5.3 The distance between two dot defect ≧5 mm.
</td><td>Minor</td></tr>
</table>

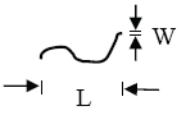
◆Specification For TFT-LCD Module Less Than 3.5″：

(Ver.B01)

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td>06</td><td>Black or white dot、scratch、contamination

Round type
 

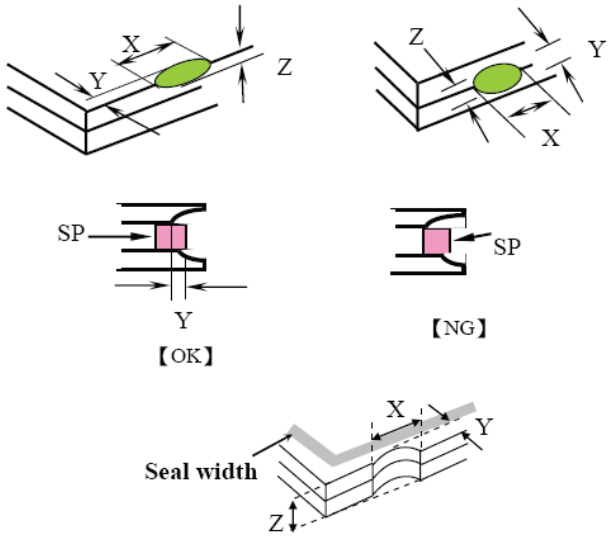
Φ=(x+y) / 2

Line type
 
</td><td>6.1 Round type (Non-display or display)：
<table><tr><th rowspan="2">Dimension
(diameter：Φ)</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>A area</th><th>B area</th></tr><tr><td>Φ ≦ 0.15</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>0.15 ＜ Φ ≦ 0.20</td><td>2</td></tr><tr><td>0.20 ＜ Φ ≦ 0.30</td><td>2</td></tr><tr><td>Φ ＞ 0.30</td><td>0</td></tr><tr><td>Total</td><td>3</td><td></td></tr></table>
6.2 Line type(Non-display or display)：
<table><tr><th colspan="2">Dimension</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>Length (L)</th><th>Width (W)</th><th>A area</th><th>B area</th></tr><tr><td>---</td><td>W ≦ 0.03</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>L ≦5.0</td><td>0.03 ＜W ≦ 0.05</td><td>3</td></tr><tr><td>---</td><td>W ＞0.05</td><td>As round type</td></tr><tr><td colspan="2">Total</td><td>3</td></tr></table></td><td>Minor</td></tr>
<tr><td>07</td><td>Polarizer Bubble</td><td><table><tr><th rowspan="2">Dimension
(diameter：Φ)</th><th colspan="2">Acceptance (Q'ty)</th></tr><tr><th>A area</th><th>B area</th></tr><tr><td>Φ ≦ 0.20</td><td>Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>0.20 ＜ Φ ≦ 0.50</td><td>3</td></tr><tr><td>Φ ＞ 0.50</td><td>0</td></tr><tr><td>Total</td><td>3</td></tr></table></td><td>Minor</td></tr>
</table>

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td>08</td><td>The crack of glass</td><td>
Symbols :

X : The length of crack　　Y : The width of crack.
Z : The thickness of crack　　W : terminal length
t : The thickness of glass　　a : LCD side length

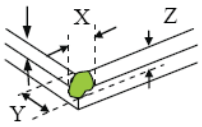
8.1 General glass chip :
8.1.1 Chip on panel surface and crack between panels:


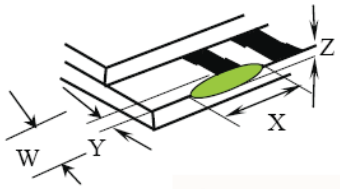
<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≦ a</td><td>Crack can't enter viewing area</td><td>≦1/2 t</td></tr>
<tr><td>≦ a</td><td>Crack can't exceed the half of SP width.</td><td>1/2 t ＜ Z ≦2 t</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

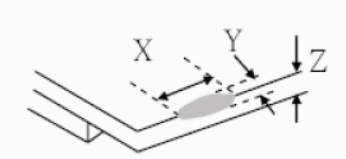
◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

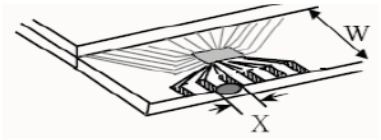
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>Level</th></tr>
<tr><td>08</td><td>The crack of glass</td><td>
Symbols :

X : The length of crack　　Y : The width of crack.
Z : The thickness of crack　　W : terminal length
t : The thickness of glass　　a : LCD side length

8.1.2 Corner crack :


<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≦1/5 a</td><td>Crack can't enter viewing area</td><td>Z ≦ 1/2 t</td></tr>
<tr><td>≦1/5 a</td><td>Crack can't exceed the half of SP width.</td><td>1/2 t < Z ≦ 2 t</td></tr>
</table>
8.2 Protrusion over terminal :
8.2.1 Chip on electrode pad :


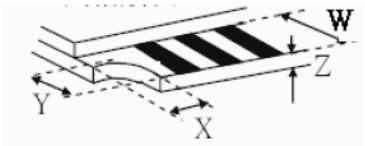
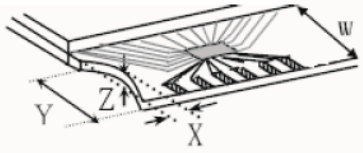
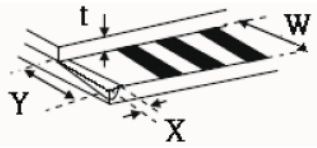
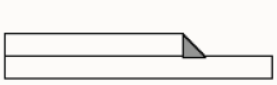
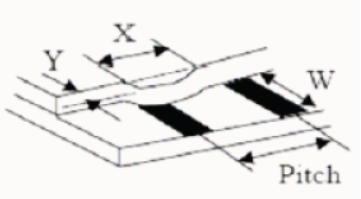




<table>
<tr><th></th><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>Front</td><td>≦ a</td><td>≦ 1/2 W</td><td>≦ t</td></tr>
<tr><td>Back</td><td>≦ a</td><td>≦ W</td><td>≦ 1/2 t</td></tr>
</table>
</td><td>Minor</td></tr>
</table>

◆Specification For TFT-LCD Module Less Than 3.5″：

(Ver.B01)

NO	Item	Criterion	Level
08	The crack of glass	Symbols： X : The length of crack　　Y : The width of crack. Z : The thickness of crack　　W : terminal length t : The thickness of glass　　a : LCD side length 8.2.2 Non-conductive portion：    X ≦ 1/3 a ; Y ≦ W ; Z ≦ t ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. 8.2.3 Glass remain：   X ≦ a ; Y ≦ 1/3 W ; Z ≦ t	Minor

◆Specification For TFT-LCD Module Less Than 3.5″ : (Ver.B01)

NO	Item	Criterion	Level
09	Backlight elements	9.1 Backlight can't work normally.	Major
		9.2 Backlight doesn't light or color is wrong.	Major
		9.3 Illumination source flickers when lit.	Major
10	General appearance	10.1 Pin type、quantity、dimension must match type in structure diagram.	Major
		10.2 No short circuits in components on PCB or FPC .	Major
		10.3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
		10.4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10.5 The folding and peeled off in polarizer are not acceptable.	Minor
		10.6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≦1.5 mm.	Minor

4. RELIABILITY TEST

4.1 Reliability Test Condition (Ver.B01)

NO.	TEST ITEM	TEST CONDITION
1	High Temperature Storage Test	Keep in 80 ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.
2	Low Temperature Storage Test	Keep in -30 ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.
3	High Temperature / High Humidity Storage Test	Keep in +60 ℃ / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)
4	Temperature Cycling Storage Test	-30℃→ +25℃ → 80℃ → +25℃ (30mins) (5mins) (30mins) (5mins) 10 Cycle Surrounding temperature, then storage at normal condition 4hrs.
5	ESD Test	Air Discharge: Apply 2 KV with 5 times Discharge for each polarity +/- Contact Discharge: Apply 250 V with 5 times discharge for each polarity +/- 1. Temperature ambiance : 15℃～35℃ 2. Humidity relative : 30%～60% 3. Energy Storage Capacitance(Cs+Cd) : 150pF±10% 4. Discharge Resistance(Rd) : 330Ω±10% 5. Discharge, mode of operation : Single Discharge (time between successive discharges at least 1 sec) (Tolerance if the output voltage indication : ±5%)
6	Vibration Test (Packaged)	1. Sine wave 10～55 Hz frequency (1 min/sweep) 2. The amplitude of vibration :1.5 mm 3. Each direction (X、Y、Z) duration for 2 Hrs
7	Drop Test (Packaged)	Packing Weight (Kg) / Drop Height (cm): 0 ~ 45.4 : 122 45.4 ~ 90.8 : 76 90.8 ~ 454 : 61 Over 454 : 46 Drop Direction :※1 corner / 3 edges / 6 sides each 1time

5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.

5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

5.2 HANDLING

5.2.1 Avoid any strong mechanical shock which can break the glass.

5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.

5.2.3 Do not remove the panel or frame from the module.

5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)

5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.

5.2.6 Do not touch the display area with bare hands , this will stain the display area.

5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.

5.2.8 To control temperature and time of soldering is 320 ± 10°C and 3-5 sec.

5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.

5.3.2 Do not place the module near organics solvents or corrosive gases.

5.3.3 Do not crush , shake , or jolt the module.

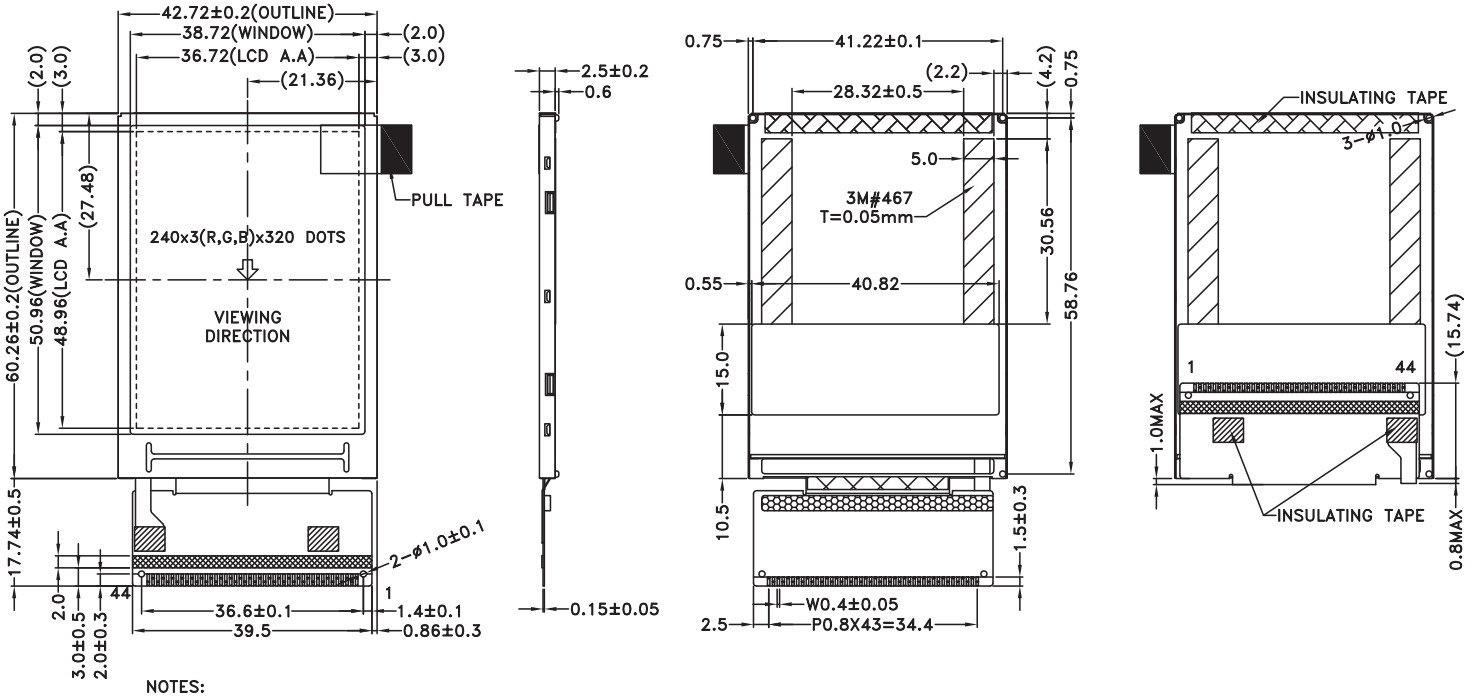
5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment , fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



NOTES:
1.)THE TOLERANCE UNLESS CLASSFIED ±0.2mm
THE R FOR NOT ASSIGNED 0.5±0.1mm
2.)LCD TYPE:a-Si TFT
3.)DRIVER IC:ST7781R
4.) COMPONENT AREA HEIGHT 1.0 MAX.
5.) DOUBLE TAPE(t=0.05mm)
6.) THIS PRODUCT CONFORMS ROHS
7.)THE REFERENCE DIMENSION LABEL( )

REV	REV BY	REVISER	DATE
007			
006			
005			
004			
003			
002			
001	NEW DRAWING	Shawn	2010/3/16

PART NO: RH240320T-2x4WN-B2

DRAWING NAME :

TITLE: LCD MODULE DRAWING

Design	Terry	(3)	Surface		
Check	Eddy	Unit	MM	Material	
Approve	Ryan	Scale	1:1	Thickness	
		Page	1/1	Quantity	

公差精度等級 / 最小長度 (mm)	精級
1 ~ 4	-
4 ~ 16	-
16 ~ 63	-
63 ~ 250	-
250 ~ 1000	-

PT-A-054-01